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# IRF5852PbF

HEXFET® Power MOSFET

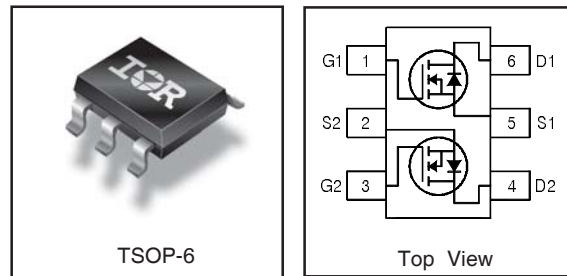
- Ultra Low On-Resistance
- Dual N-Channel MOSFET
- Surface Mount
- Available in Tape & Reel
- Low Gate Charge
- Lead-Free
- Halogen-Free

$V_{DSS}$	$R_{DS(on)}$ max ( $\Omega$ )	$I_D$
20 V	0.090 @ $V_{GS} = 4.5V$	2.7A
	0.120 @ $V_{GS} = 2.5V$	2.2A

## Description

These N-channel MOSFETs from International Rectifier utilize advanced processing techniques to achieve the extremely low on-resistance per silicon area. This benefit provides the designer with an extremely efficient device for use in battery and load management applications.

This Dual TSOP-6 package is ideal for applications where printed circuit board space is at a premium and where maximum functionality is required. With two die per package, the IRF5852 can provide the functionality of two SOT-23 packages in a smaller footprint. Its unique thermal design and  $R_{DS(on)}$  reduction enables an increase in current-handling capability.



## Absolute Maximum Ratings

	Parameter	Max.	Units
$V_{DS}$	Drain- Source Voltage	20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	2.7	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	2.2	
$I_{DM}$	Pulsed Drain Current ①	11	
$P_D @ T_A = 25^\circ C$	Power Dissipation ③	0.96	W
$P_D @ T_A = 70^\circ C$	Power Dissipation ③	0.62	
	Linear Derating Factor	7.7	mW/°C
$V_{GS}$	Gate-to-Source Voltage	$\pm 12$	V
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to + 150	°C

## Thermal Resistance

	Parameter	Max.	Units
$R_{\theta JA}$	Maximum Junction-to-Ambient ③	130	°C/W

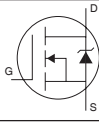
# IRF5852PbF

International  
IR Rectifier

## Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	20	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.016	—	V/°C	Reference to $25^\circ\text{C}, I_D = 1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.090	$\Omega$	$V_{GS} = 4.5V, I_D = 2.7A$ ②
		—	—	0.120		$V_{GS} = 2.5V, I_D = 2.2A$ ②
$V_{GS(th)}$	Gate Threshold Voltage	0.60	—	1.25	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
$g_{fs}$	Forward Transconductance	5.2	—	—	S	$V_{DS} = 10V, I_D = 2.7A$
$I_{DSS}$	Drain-to-Source Leakage Current	—	—	1.0	$\mu A$	$V_{DS} = 16V, V_{GS} = 0V$
		—	—	25		$V_{DS} = 16V, V_{GS} = 0V, T_J = 70^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 12V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -12V$
$Q_g$	Total Gate Charge	—	4.0	6.0	nC	$I_D = 2.7A$
$Q_{gs}$	Gate-to-Source Charge	—	0.95	—		$V_{DS} = 16V$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge	—	0.88	—		$V_{GS} = 4.5V$ ②
$t_{d(on)}$	Turn-On Delay Time	—	6.6	—	ns	$V_{DD} = 10V$ ②
$t_r$	Rise Time	—	1.2	—		$I_D = 1.0A$
$t_{d(off)}$	Turn-Off Delay Time	—	15	—		$R_G = 6.2\Omega$
$t_f$	Fall Time	—	2.4	—		$V_{GS} = 4.5V$
$C_{iss}$	Input Capacitance	—	400	—	pF	$V_{GS} = 0V$
$C_{oss}$	Output Capacitance	—	48	—		$V_{DS} = 15V$
$C_{rss}$	Reverse Transfer Capacitance	—	32	—		$f = 1.0\text{MHz}$

## Source-Drain Ratings and Characteristics

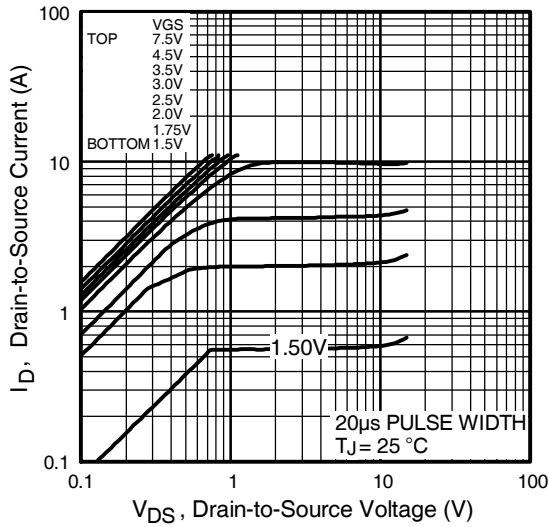
	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	0.96	A	MOSFET symbol showing the integral reverse p-n junction diode. 
$I_{SM}$	Pulsed Source Current (Body Diode) ①	—	—	11		
$V_{SD}$	Diode Forward Voltage	—	—	1.2	V	$T_J = 25^\circ\text{C}, I_S = 0.96A, V_{GS} = 0V$ ②
$t_{rr}$	Reverse Recovery Time	—	25	38	ns	$T_J = 25^\circ\text{C}, I_F = 0.96A$
$Q_{rr}$	Reverse Recovery Charge	—	6.5	9.8	nC	$di/dt = 100A/\mu s$ ②

### Notes:

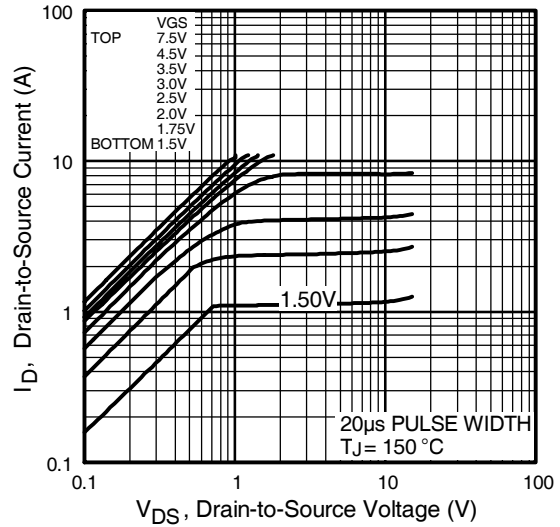
① Repetitive rating; pulse width limited by max. junction temperature.

② Pulse width  $\leq 400\mu s$ ; duty cycle  $\leq 2\%$ .

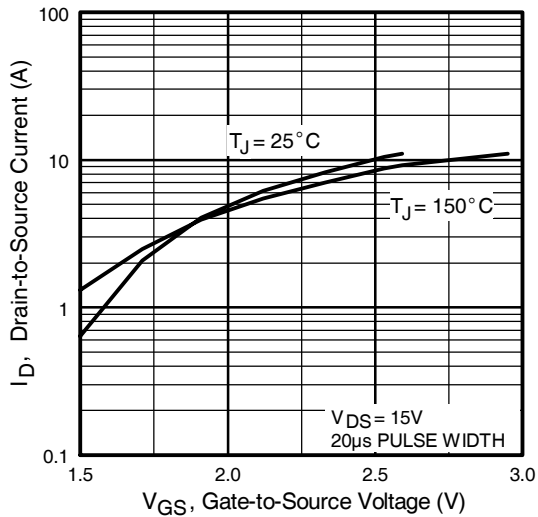
③ Surface mounted on FR-4 board,  $t \leq 5\text{sec}$ .



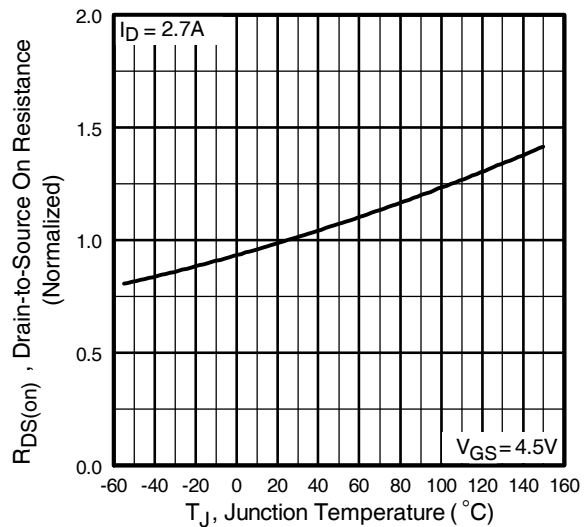
**Fig 1.** Typical Output Characteristics



**Fig 2.** Typical Output Characteristics



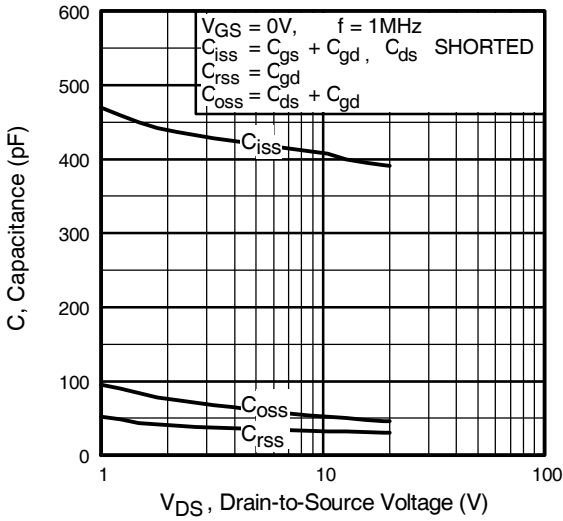
**Fig 3.** Typical Transfer Characteristics



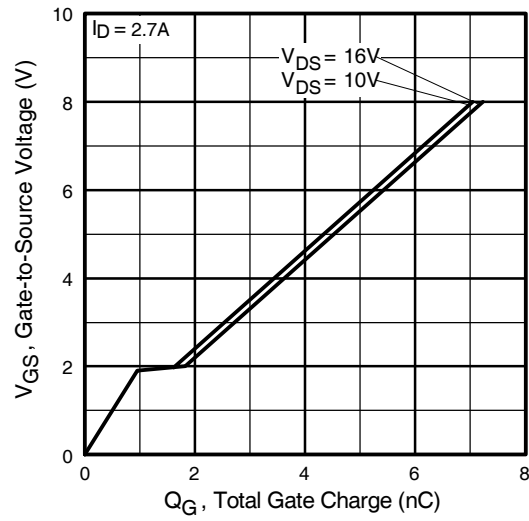
**Fig 4.** Normalized On-Resistance Vs. Temperature

# IRF5852PbF

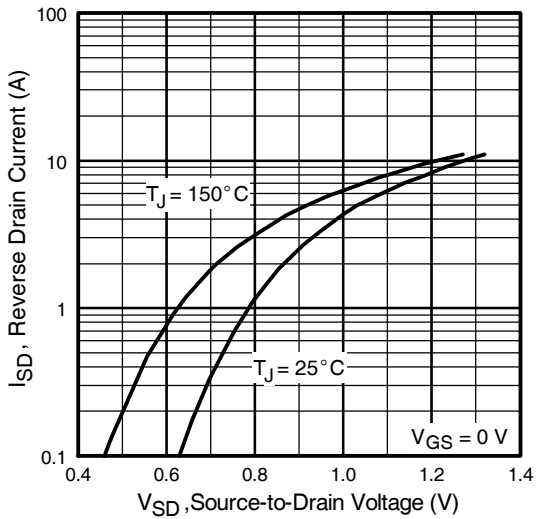
International  
**IR** Rectifier



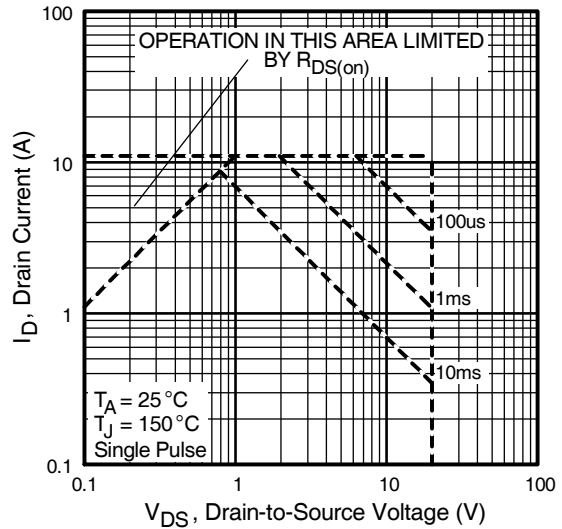
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



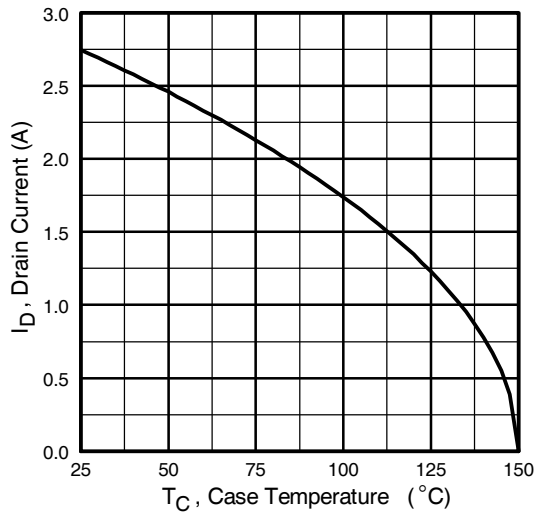
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



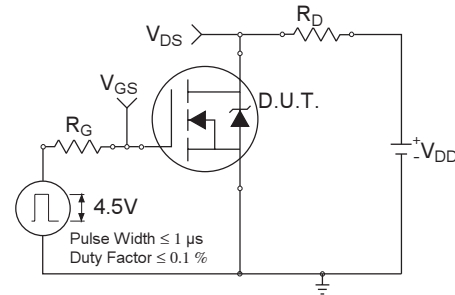
**Fig 7.** Typical Source-Drain Diode Forward Voltage



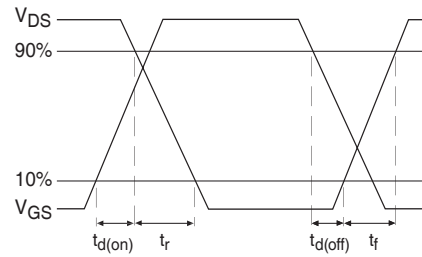
**Fig 8.** Maximum Safe Operating Area



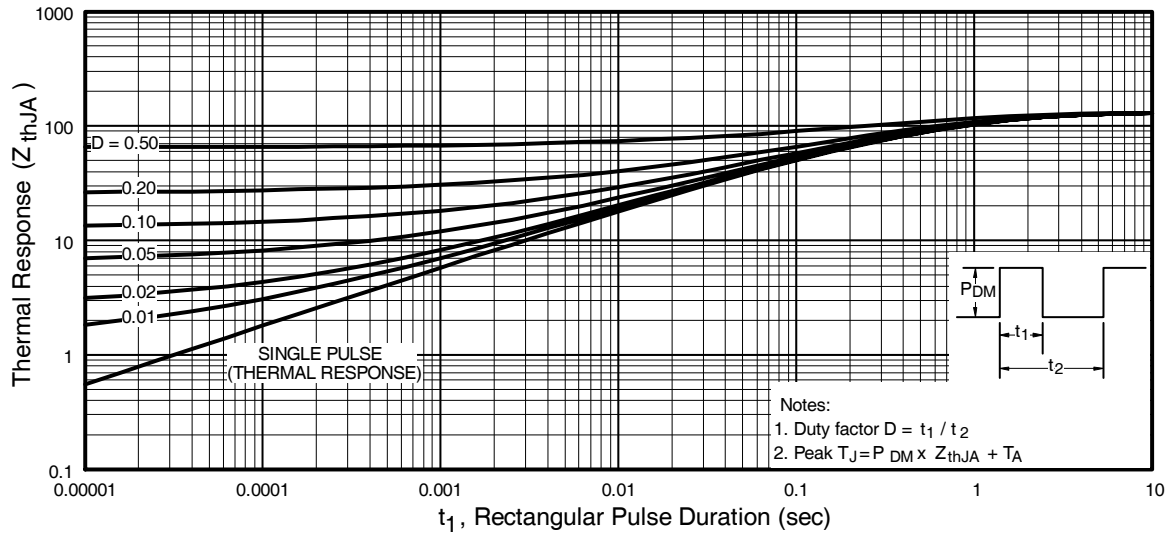
**Fig 9.** Maximum Drain Current Vs. Case Temperature



**Fig 10a.** Switching Time Test Circuit



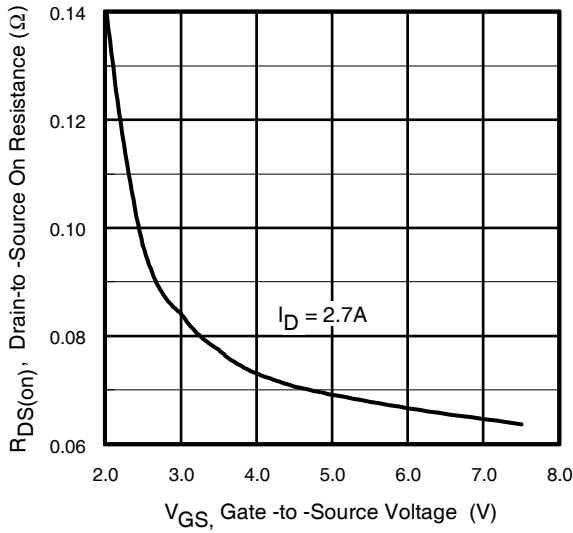
**Fig 10b.** Switching Time Waveforms



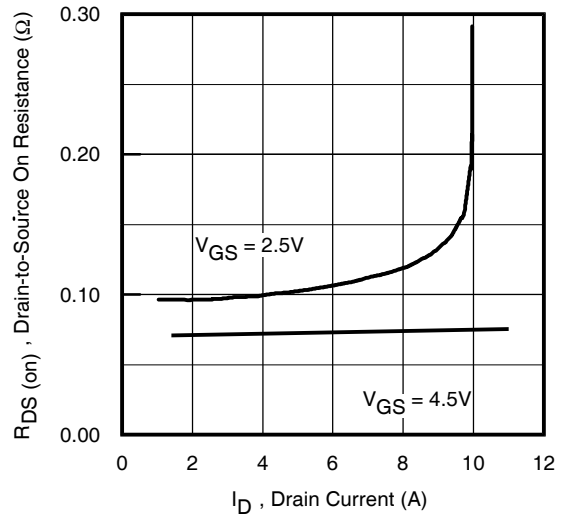
**Fig 10.** Typical Effective Transient Thermal Impedance, Junction-to-Ambient

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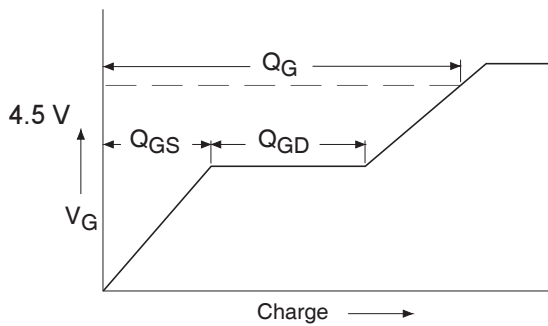
International  
**IR** Rectifier



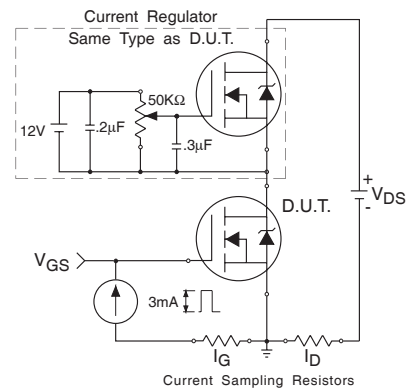
**Fig 11.** Typical On-Resistance Vs. Gate Voltage



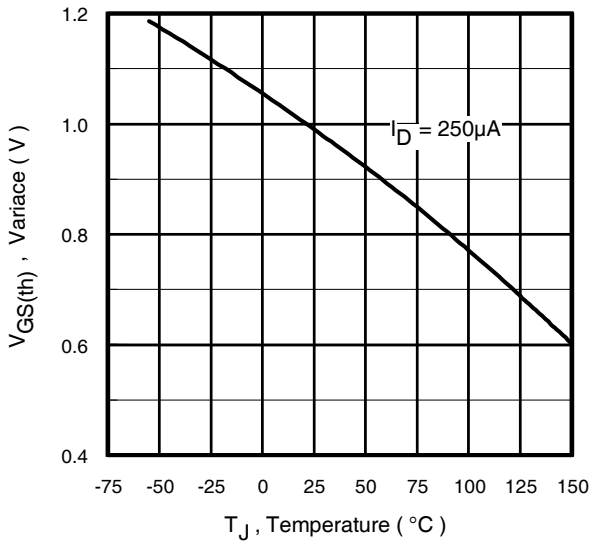
**Fig 12.** Typical On-Resistance Vs. Drain Current



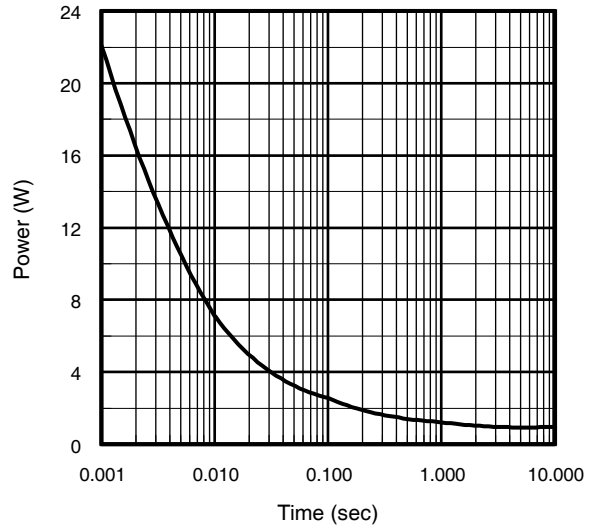
**Fig 13a.** Basic Gate Charge Waveform



**Fig 13b.** Gate Charge Test Circuit



**Fig 14.** Threshold Voltage Vs. Temperature

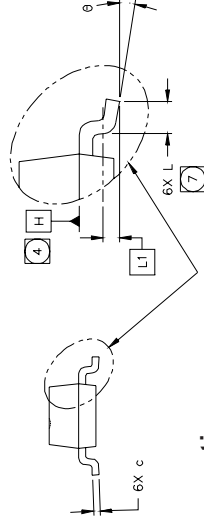
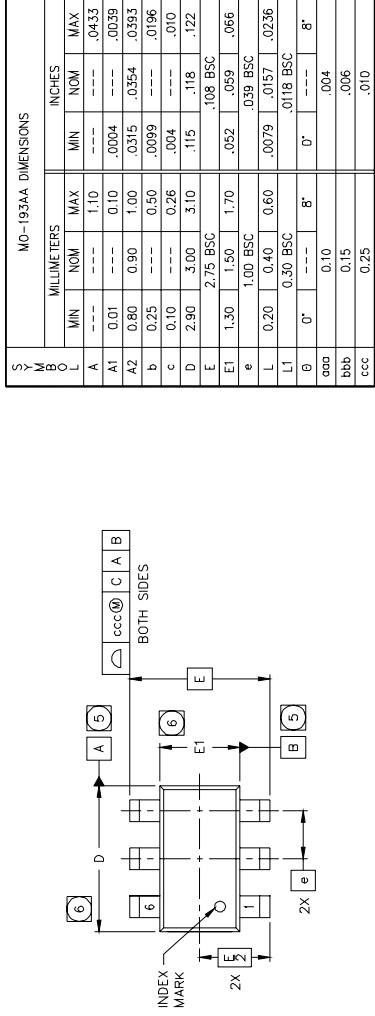


**Fig 15.** Typical Power Vs. Time

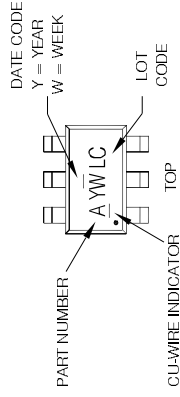


# IRF5852PbF

## TSOP-6 Package Outline



## TSOP-6 Part Marking Information



### PART NUMBER CODE REFERENCE:

- A = S13443DV
- B = IRF5800
- C = IRF5850
- D = IRF5851
- E = IRF5852
- F = IRF5801
- I = IRF5805
- J = IRF5806
- K = IRF5810
- L = IRF5804
- M = IRF5803
- N = IRF5802

### Notes:

- A line above the work week (as shown here) indicates Lead-Free
- A line below the part number (as shown here) indicates Cu-wire

W = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR

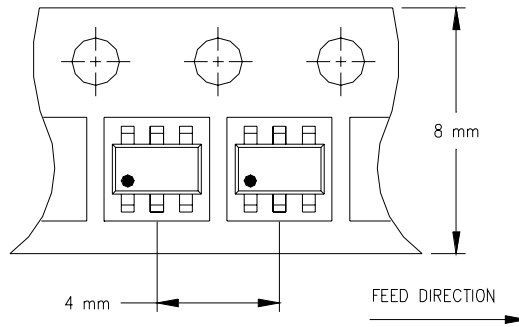
YEAR	Y	WORK WEEK	W
2001	1	01	A
2002	2	02	B
2003	3	03	C
2004	4	04	D
2005	5		
2006	6		
2007	7		
2008	8		
2009	9		
2010	0	24	X
		25	Y
		26	Z

W = (27-52) IF PRECEDED BY A LETTER

YEAR	Y	WORK WEEK	W
2001	A	27	A
2002	B	28	B
2003	C	29	C
2004	D	30	D
2005	E		
2006	F		
2007	G		
2008	H		
2009	J		
2010	K	50	X
		51	Y
		52	Z

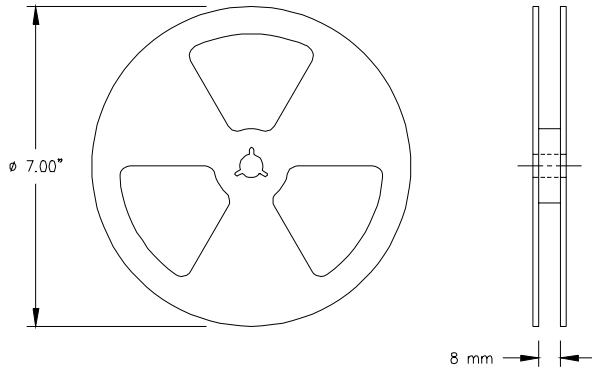
Note: For the most current drawing please refer to IR website at: <http://www.irf.com/package/>

## TSOP-6 Tape & Reel Information



NOTES:

1. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES:

1. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Data and specifications subject to change without notice.  
This product has been designed and qualified for the Consumer market.  
Qualification Standards can be found on IR's Web site.